



- ① Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. non clad
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

**Description:** Giga-snaP BGA SMT Land Socket  
625 position BGA surface mount land pattern to terminal pins (0.8mm centers, 25x25 array)

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>LS-BGA625C-61 Drawing</b>		Status: Released	Scale: 5:1	Rev: C
	© 2005 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: S.Natarajan		Date: 5/12/05
		File: LS-BGA625C-61 Dwg.mcd		Modified: 01/18/13, DH